


# MATERIAL DECLARATION SHEET



Material Number	CDSOT236-0504LC			
Product Line	Semiconductor Products			
Compliance Date	2015/8/28			
RoHS Compliant	Yes	MSL	3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	0.13015	Silicon	7440-21-3	100.00%	0.846%	0.846%
2	Lead frame	Copper Alloy	5.91455	Copper	7440-50-8	93.829%	38.475%	41.006%
			0.13864	Iron	7439-89-6	2.205%	0.904%	
			0.00756	Phosphorus	7723-14-0	0.127%	0.052%	
			0.00756	Zinc	7440-66-6	0.127%	0.052%	
			0.00050	Lead	7439-92-1	0.016%	0.007%	
			0.23317	Silver	7440-22-4	3.696%	1.516%	
3	Epoxy	Polymer	0.01638	Si-oxide Quartz	14808-60-7	41.379%	0.078%	0.189%
			0.00624	Epoxy resin	Confidential	41.379%	0.078%	
			0.00585	Epoxy resin modifier	Confidential	13.794%	0.026%	
			0.00117	Aromatic amine	Confidential	3.448%	0.007%	
4	Cu Wire	Noble metal	0.15680	Copper	7440-50-8	98.125%	1.021%	1.041%
			0.00320	Palladium	7440-05-3	1.875%	0.020%	
5	Mold Compound	Polymer	0.80600	Solid Epoxy Resin	Confidential	10.000%	5.243%	52.429%
			0.80600	Phenol Resin	Confidential	10.000%	5.243%	
			5.48080	Fused Silica	60676-86-0	68.003%	35.653%	
			0.04030	Carbon Black	1333-86-4	0.496%	0.260%	
			0.80600	Metal Hydroxide	Confidential	10.000%	5.243%	
			0.12090	Catalyst	Confidential	1.501%	0.787%	

# MATERIAL DECLARATION SHEET



6	Plating	Plating	0.68890	Tin	7440-31-5	99.855%	4.482%	4.489%
			0.00069	Misc, not to declare	/	0.145%	0.007%	
		Total weight	<b>15.37136 mg</b>					

This Document was updated on: 2015/11/27

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.